

DECLARATION

As the below-named inventors, we declare that:

Our residences, post office addresses, and citizenships are as stated below under our names.

We believe we are the original, first, and joint inventors of the invention entitled "SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY ISOLATING MODULES," which is described and claimed in the foregoing application and for which a patent is sought. This application claims the benefit of earlier filed United Kingdom Patent Application No. 0126821.8, filed on November 7, 2001.

We have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment specifically referred to herein (if any).

We acknowledge our duty to disclose information of which we are aware which is material to patentability and examination of this application in accordance with 37 C.F.R. § 1.56(a).

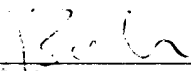
We further declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.

Applicants' counsel is authorized to insert the official filing date and application number information when it becomes available.



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Date 02 January 2002
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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Sion C. Quinlan and Tim J. Bales Attorney Docket No.: 500986.02
Filed : Concurrently herewith
Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY
ISOLATING MODULES

Box Patent Application
Commissioner of Patents
Washington, DC 20231

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73(b) AND POWER OF ATTORNEY

Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment filed concurrently herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventors.

Assignee hereby appoints EDWARD W. BULCHIS, Reg. No. 26,847; PAUL T. MEIKLEJOHN, Reg. No. 26,569; GLENN P. RICKARDS, Reg. No. 29,428; DALE C. BARR, Reg. No. 40,498; KIMTON N. ENG, Reg. No. 43,605; BRIAN C. PARK, Reg. No. 45,519; MARK W. ROBERTS, Reg. No. 46,160; STEVEN H. ARTERBERRY, Reg. No. 46,314; PAUL F. RUSYN, Reg. No. 42,118; ANDREW F. PRATT, Reg. No. 48,985; FRANK J. BOZZO, Reg. No. 36,756; JAMES ACKLEY, Reg. No. 45,695; RONALD BROWN, Reg. No. 29,016; DAVID BRUHN, Reg. No. 36,762; MARK CARLSON, Reg. No. 27,105; KEVIN CHAPPLE, Reg. No. 44,072; W. ROBINSON CLARK, Reg. No. 41,530; SHANE COLEMAN, Reg. No. 44,623; GREGORY DURBIN, Reg. No. 42,503; DANIEL FISHER, Reg. No. 34,162; DAVID FRONEK, Reg. No. 25,678; ANTHONY GANGEMI, Reg. No. 42,565; MICHAEL GILCHRIST, Reg. No. 40,619; THERESA HANKES, Reg. No. 45,501; JOHN HARROP, Reg. No. 41,817; BRAD HATTENBACH, Reg. No. 42,642; REED HEIMBECHER, Reg. No. 36,353; CRAIG HEMENWAY, Reg. No. 44,759; STUART HEMPHILL, Reg. No. 28,084; MARK HOGGE, Reg.

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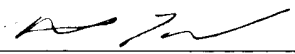
Please direct all communications to:

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Pursuant to 37 C.F.R. § 3.73(b), the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., filed concurrently herewith for recording, a copy of which is attached hereto, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

MICRON TECHNOLOGY, INC.
ASSIGNEE

1-14-2002
DATE


Michael L. Lynch
Chief Patent Counsel

Enclosure:
Copy of Assignment

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